



## Tflex™ B200 Thermal Gap Filler

Tflex™ B200, designed for improved EV battery pack cooling, is introduced as a reliable and compliant gap filler thermal interface material with good thermal performance and easier handling. Tflex B200 has multiple surface and enforcement options and is ideal for a variety of applications.

### **Tflex B200 offers these FEATURES AND BENEFITS**

- Thermal Conductivity of 2W/m.K
- Softness relieves mechanical stress
- Compliant to application surfaces, long term reliability
- Shock resistance in automotive applications
- Fiberglass enforcement, protects against breakthrough or deforming
- Protection with high DBV

Please review these resource materials:

[Tflex™ B200 Application Note \(English version\)](#)

[Tflex™ B200 Datasheet \(English version\)](#)

